



US00D814433S

(12) **United States Design Patent**
Soyano et al.

(10) **Patent No.:** **US D814,433 S**
(45) **Date of Patent:** **** Apr. 3, 2018**

(54) **SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

(21) Appl. No.: **29/580,736**

(22) Filed: **Oct. 12, 2016**

Related U.S. Application Data

(62) Division of application No. 29/528,214, filed on May 27, 2015, now Pat. No. Des. 774,479.

(30) **Foreign Application Priority Data**

Nov. 28, 2014	(JP)	D2014-026634
Nov. 28, 2014	(JP)	D2014-026635
Nov. 28, 2014	(JP)	D2014-026636

(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 257/678, 684, 690, 691;
361/679.01, 713, 728, 736, 760, 761, 772,
(Continued)

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(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a semiconductor module showing our new design.

FIG. 2 is a rear view of the semiconductor module of FIG. 1.

FIG. 3 is a left side view of the semiconductor module of FIG. 1.

FIG. 4 is a right side view of the semiconductor module of FIG. 1.

FIG. 5 is a top view of the semiconductor module of FIG. 1.

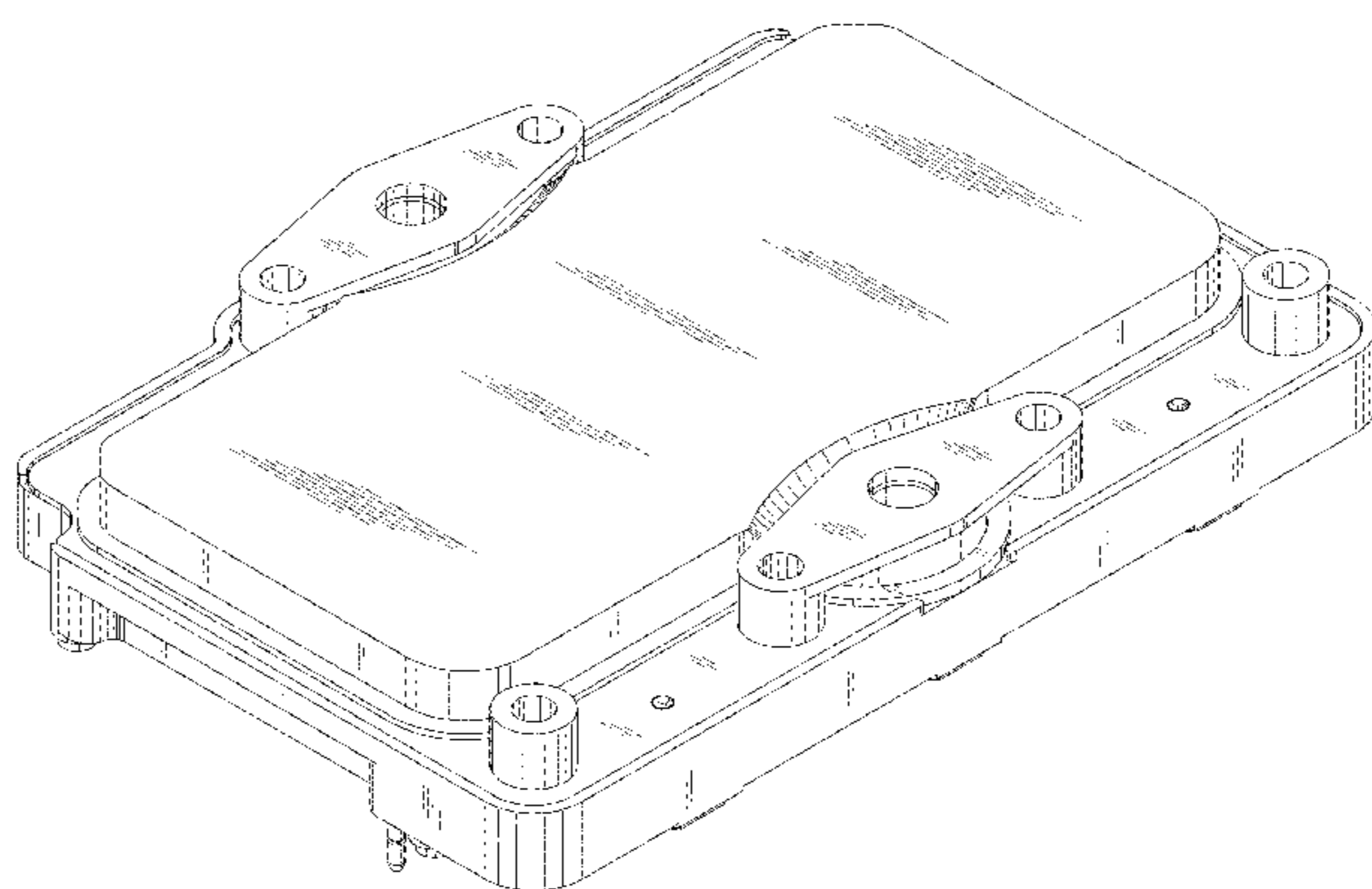
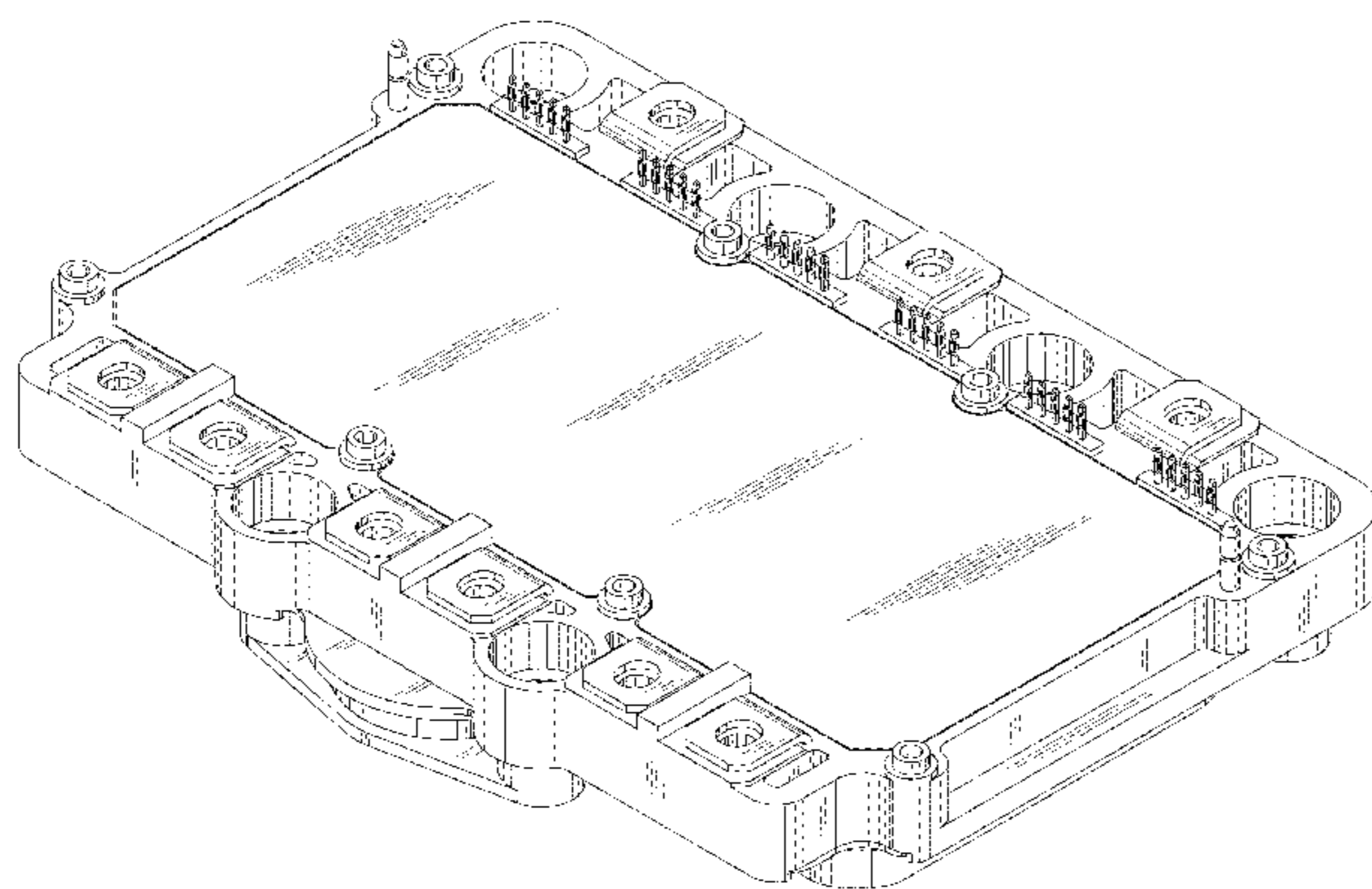
FIG. 6 is a bottom view of the semiconductor module of FIG. 1.

FIG. 7 is a front, right, and bottom perspective view of the semiconductor module of FIG. 1; and,

FIG. 8 is a rear, left, and top perspective view of the semiconductor module of FIG. 1.

The ornamental design of the present disclosure is a semiconductor module on which power semiconductor elements and the like may be mounted. Terminals extend from a circumferential edge part of a front surface. Rhombic plate members having rounded corners are centered along the long sides of the rear view, such that the longer diagonal line of each rhombic plate member extends along a long side.

1 Claim, 8 Drawing Sheets



(58) **Field of Classification Search**

USPC 361/775, 783, 820; 174/250, 253;
 438/15, 25, 26, 51, 55, 63, 64, 106
 CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
 H01L 2021/00; H01L 2021/02; H01L
 2021/04; H01L 21/4814; H01L 21/4846;
 H01L 21/4871; H01L 21/67144; H01L
 23/02; H01L 23/13; H01L 23/14; H01L
 23/147; H01L 2924/171; H01L
 2924/1711; H01L 2924/1715; H01L
 2924/17151; H01L 2924/181; H01L
 2924/1811; H01L 2924/1815; H01L
 2924/19042; H01L 2924/1905; H01L
 2224/08054; H01L 23/58; H05B 41/14;
 H02B 6/4201; G02B 6/4256; G02B
 6/4257; G02B 6/4261; G02B 6/4262;
 G02B 6/428; G02B 6/4281; H05K 1/14;
 H05K 1/141; H05K 1/142; H05K 1/144;
 H05K 1/18; H05K 1/181; H05K 1/182;
 H05K 1/026

See application file for complete search history.

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FIG. 1

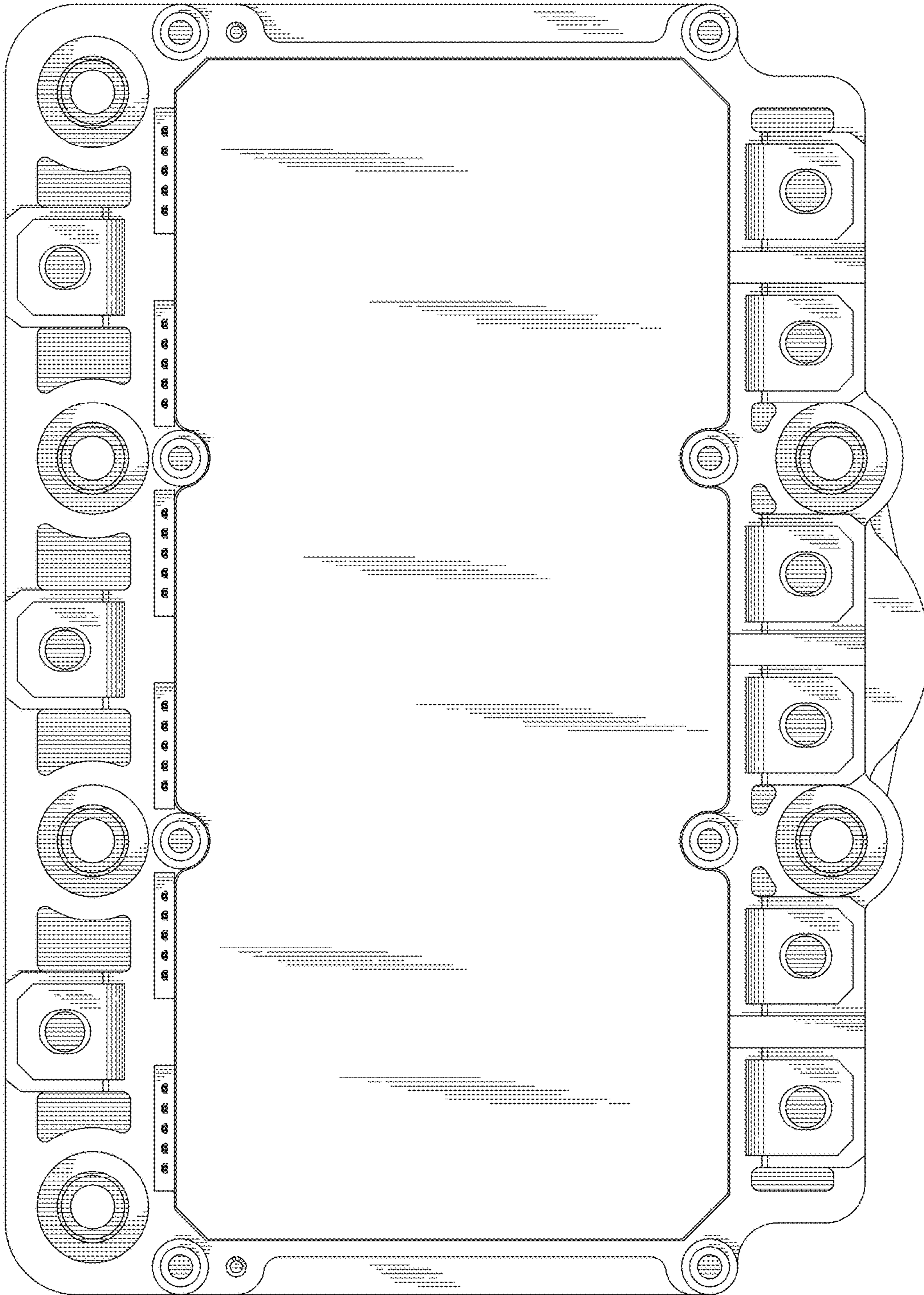


FIG. 2

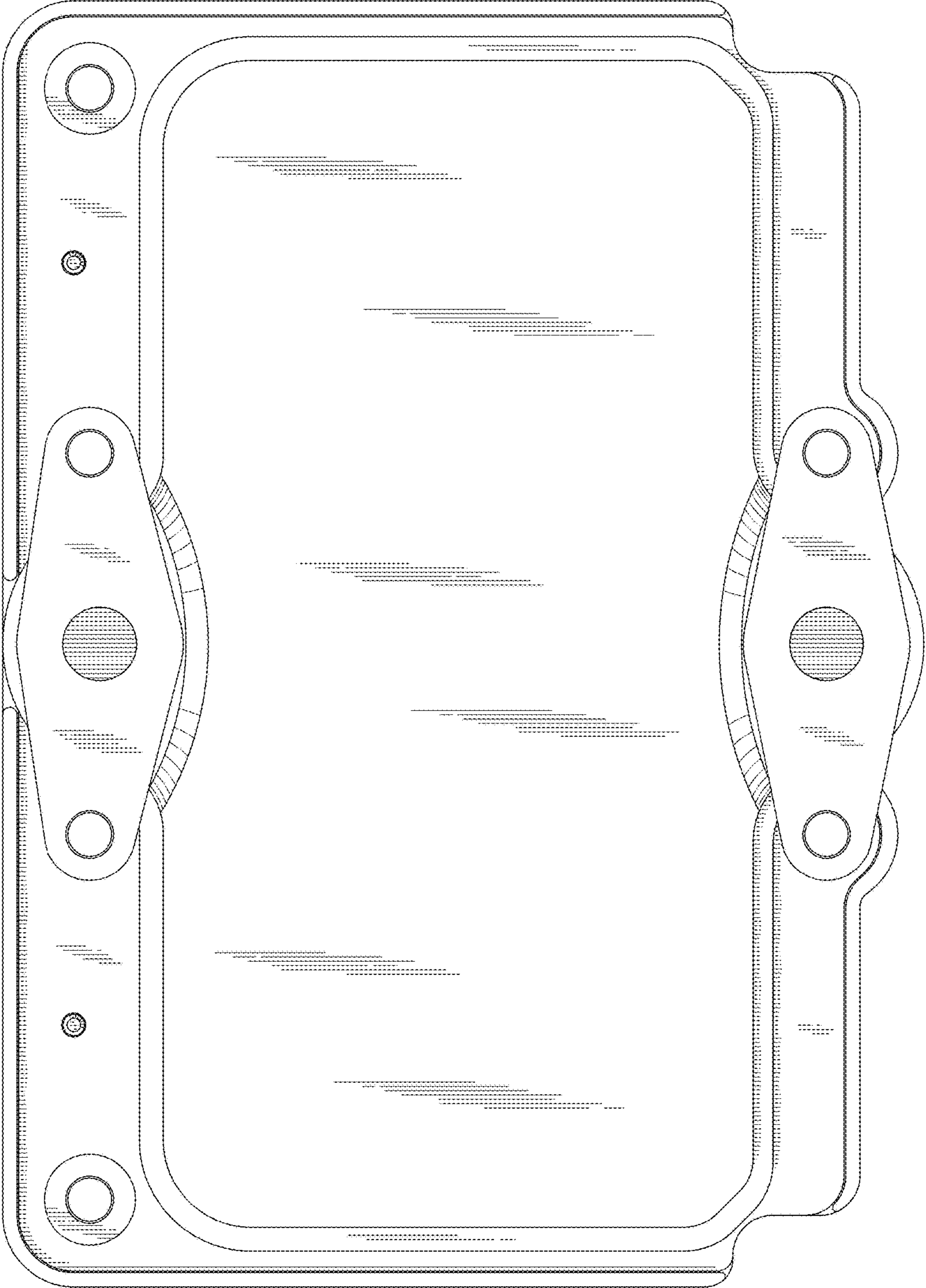


FIG. 3

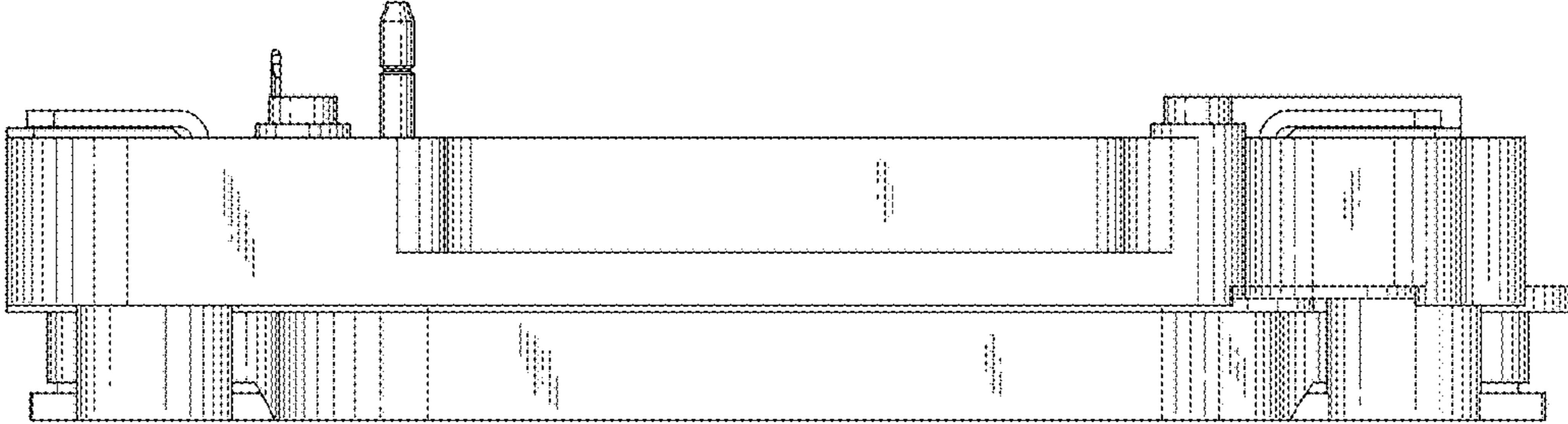


FIG. 4

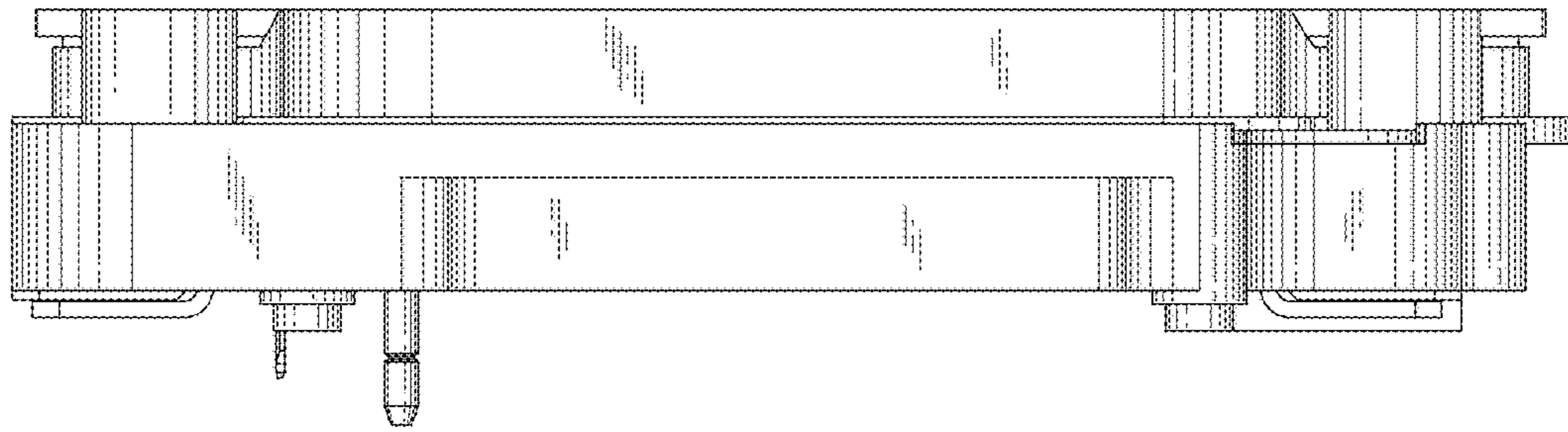


FIG. 5

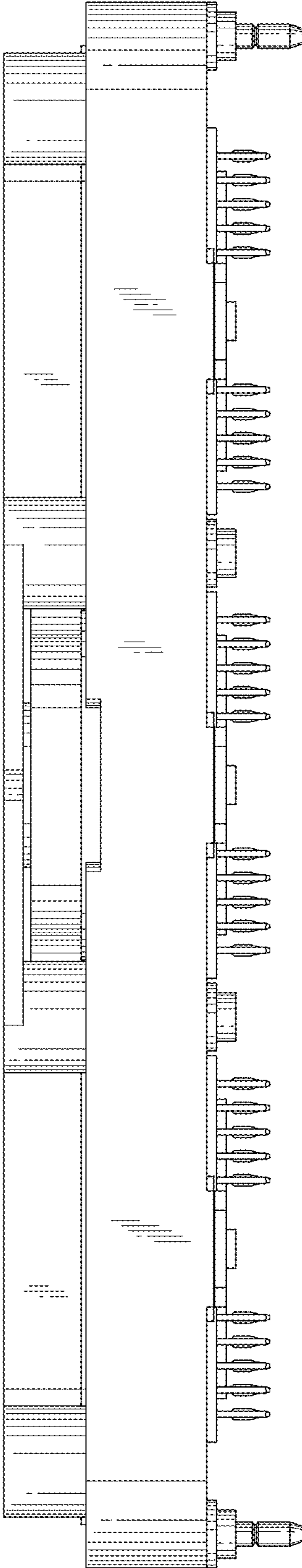


FIG. 6

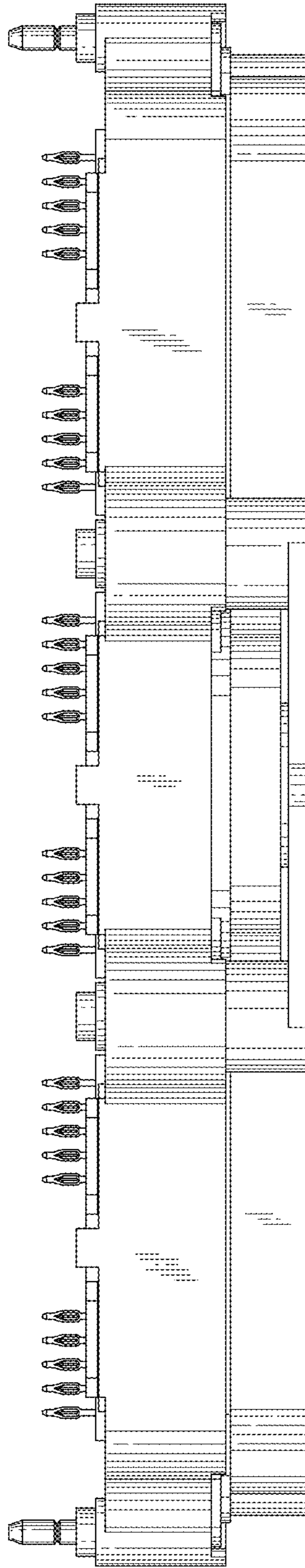


FIG. 7

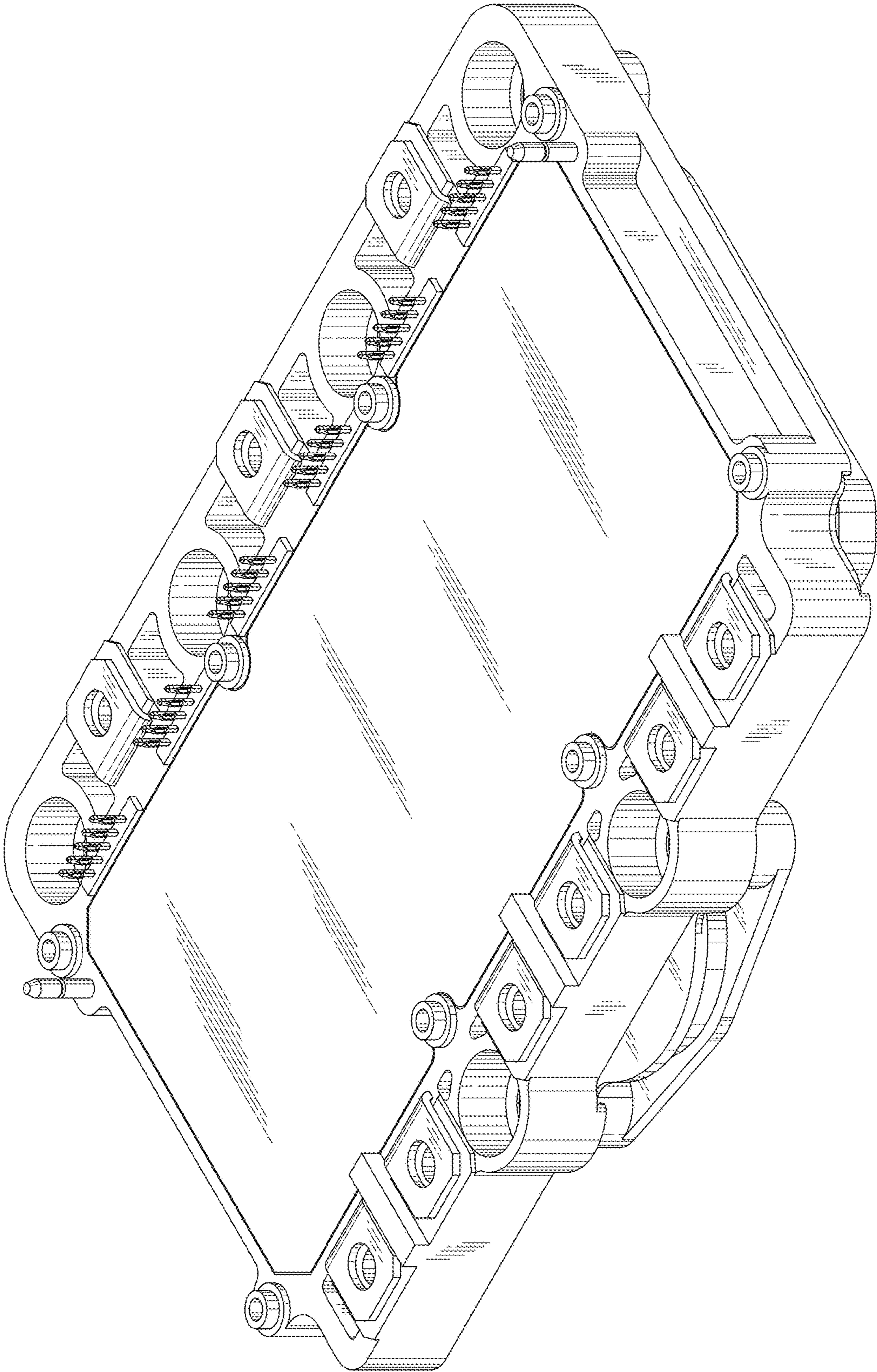


FIG. 8

